查询BD6381EFV供应商

ROHM 1/4

STRUCTURE Silicon monolithic integrated circuits

PRODUCT SERIES Bipolar stepping motor driver

TYPE BD6381EFV

FUNCTION • PWM constant current controllable two H bridge driver

· Power save mode

Reference voltage output

· Low on resistance DMOS

○Absolute maximum ratings (Ta=25°C)

Item	Symbol	Limit	Unit
Supply voltage VCC	V <sub>CC</sub>	-0.2~+7.0	V
Supply voltage VM	V <sub>M</sub>	-0.2~+15.0	V
Dawer dissination	D4 _	1.1 <sup>*1</sup>	W
Power dissipation	Pd	4.0 <sup>*2</sup>	W
Input voltage for control pin	V <sub>IN</sub>	-0.2~(V <sub>CC</sub> +0.3)	V
RNF maximum voltage	V <sub>RNF</sub>	0.5	V
Maximum output current	lout	1.2 <sup>*3</sup>	A/ch
Operating temperature range	Topr	-25~+75	°C
Storage temperature range	T <sub>stg</sub>	-55 <del>~+</del> 150	°C
Junction temperature	T <sub>jmax</sub>	150	°C

<sup>\*1 70</sup>mm×70mm×1.6mm glass epoxy board. Derating in done at 8.8mW/°C for operating above Ta=25°C

\*3 Do not exceed Pd, ASO.

Operating conditions (Ta=-25~+75℃)

perating conditions (14- 25 - 176 C)							
Item	Symbol	Min.	Тур.	Max.	Unit		
Supply voltage VCC	V <sub>cc</sub>	2.5	3.3	5.5	V		
Supply voltage VM	V <sub>M</sub>	6.0	7.2	13.5	٧		
Input voltage for control	V <sub>IN</sub>	0	-	Vcc	٧		
Output current (DC)	lout		0.6	0.8*4	A/ch		

<sup>\*4</sup> Do not exceed Pd, ASO.

This product isn't designed for protection against radioactive rays.

#### Status of this document

The Japanese version of this document is the formal specification.

A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.



<sup>\*2 4-</sup>layer recommended board. Derating in done at 32.0mW/°C for operating above Ta=25°C.



○ Electrical characteristics (Unless otherwise specified Ta=25°C、VCC=3.3V、VM=7.2V)

lk a ma	O. mala al		Limit			0	
Item	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Whole							
VCC current at standby	Iccst	-	0	10	μΑ	PS=L	
VCC current	Icc	-	1.6	3.0	mA	PS=H, VLIMX=0.5V	
VM current at standby	I <sub>VMST</sub>	-	0	10	μΑ	PS=L	
VM current	I <sub>VM</sub>	-	0.09	0.50	mA	PS=H, VLIMX=0.5V	
Control input (PS, IN1A, IN1B, II	N2A, IN2B)						
H level input voltage	V <sub>INH</sub>	2.0	-	3.3	٧		
L level input voltage	V <sub>INL</sub>	0	-	0.8	٧		
H level input current	I <sub>INH</sub>	15	30	60	μΑ	V <sub>IN</sub> =3V	
L level input current	l <sub>INL</sub>	-10	0	-	μΑ	V <sub>IN</sub> =0V	
Output (OUT1A, OUT1B, OUT2A, OUT2B)							
Output ON resistance	Ron	-	1.0	1.25	Ω	$I_{OUT} = \pm 0.6A, VM = 7.2V$	
	TION					Sum of upper and lower	
Output leak current	I <sub>LEAK</sub>	-	-	10	μΑ		
Current control							
RNFX input current	I <sub>RNF</sub>	-40	-20	-	μΑ	RNFX=0V	
SENSEX input current	I <sub>SENSE</sub>	-2.0	-0.1	-	μΑ	SENSEX=0V	
VLIMX input current	I <sub>VLIM</sub>	-2.0	-0.1	-	μΑ	VLIMX=0V	
VLIMX input voltage range	V <sub>VLIM</sub>	0	-	0.5	٧		
Comparator offset voltage	V <sub>OFS</sub>	-10	-	10	mV		
Noise cancel time	t <sub>n</sub>	0.3	0.7	1.2	μs	R=39kΩ, C=1000pF	
VREF voltage	V <sub>VREF</sub>	0.97	1.00	1.03	٧	I <sub>VREF</sub> =0~1mA	

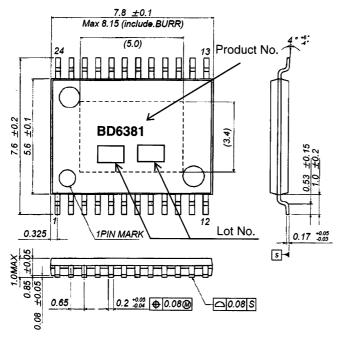
O Input-output logic table

	INPUT		OUTPUT		
	IN1A	IN1B	OUT1A	OUT1B	
PS	IN2A	IN2B	OUT2A	OUT2B	
L	Х	Х	OPEN	OPEN	All circuit Standby
Н	L	L	OPEN	OPEN	Standby
Н	Н	L	Н	L	Forward
Н	L	Н	L	Н	Backward
Н	Н	Ι	L	L	Brake

X: H or L

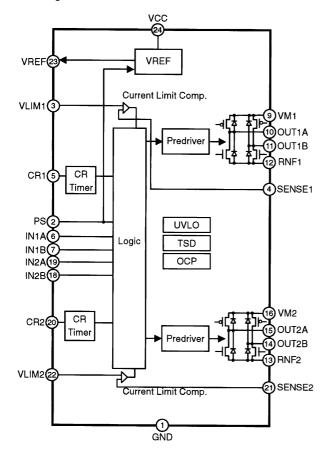
# ROHM

# O Package outline



HTSSOP-B24 (Unit:mm)

# OBlock diagram



○Pin No. / Pin name

Pin No.	Pin name	Pin No.	Pin name
1	GND	13	RNF2
2	PS	14	OUT2B
3	VLIM1	15	OUT2A
4	SENSE1	16	VM2
5	CR1	17	NC
6	IN1A	18	IN2B
7	IN1B	19	IN2A
8	NC	20	CR2
9	VM1	21	SENSE2
10	OUT1A	22	VLIM2
11	OUT1B	23	VREF
12	RNF1	24	VCC

NC: Non Connection



# Operation Notes

### (1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

#### (2) Power supply lines

As return of current regenerated by back EMF of motor happens, take steps such as putting capacitor between power supply and GND as an electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.

#### (3) GND potential

The potential of GND pin must be minimum potential in all operating conditions.

#### (4) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes its frame of the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency. Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.

# (5) Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

## (6) ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.

## (7) Thermal shutdown circuit

The IC has a built-in thermal shutdown circuit (TSD circuit). If the chip temperature becomes Tjmax=150℃, and higher, coil output to the motor will be open. The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect or indemnify peripheral equipment. Do not use the TSD function to protect peripheral equipment.

# (8) Ground Wiring Pattern

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

# Notes

- No technical content pages of this document may be reproduced in any form or transmitted by any means without prior permission of ROHM CO.,LTD.
- The contents described herein are subject to change without notice. The specifications for the
  product described in this document are for reference only. Upon actual use, therefore, please request
  that specifications to be separately delivered.
- Application circuit diagrams and circuit constants contained herein are shown as examples of standard
  use and operation. Please pay careful attention to the peripheral conditions when designing circuits
  and deciding upon circuit constants in the set.
- Any data, including, but not limited to application circuit diagrams information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.
- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resell or
  otherwise dispose of the same, no express or implied right or license to practice or commercially
  exploit any intellectual property rights or other proprietary rights owned or controlled by
- ROHM CO., LTD. is granted to any such buyer.
- Products listed in this document are no antiradiation design.

The products listed in this document are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).

Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

It is our top priority to supply products with the utmost quality and reliability. However, there is always a chance of failure due to unexpected factors. Therefore, please take into account the derating characteristics and allow for sufficient safety features, such as extra margin, anti-flammability, and fail-safe measures when designing in order to prevent possible accidents that may result in bodily harm or fire caused by component failure. ROHM cannot be held responsible for any damages arising from the use of the products under conditions out of the range of the specifications or due to non-compliance with the NOTES specified in this catalog.

Thank you for your accessing to ROHM product informations.

More detail product informations and catalogs are available, please contact your nearest sales office.

ROHM Customer Support System TH

THE AMERICAS / EUPOPE / ASIA / JAPAN

Contact us : webmaster@rohm.co.jp

www.rohm.com

ROHM CO., LTD. 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto 615-8585, Japan TEL:+81-75-311-2121 FAX:+81-75-315-0172

